





140V NPN DARLINGTON TRANSISTOR IN SOT223

Features

- BV_{CEO} > 140V
- BVcso > 160V
- I_C = 2A High Continuous Current
- NPN Darlington with Gain >10k
- Guaranteed hFE Specified up to 1A
- Lead-Free Finish; RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability
- PPAP Capable (Note 5)

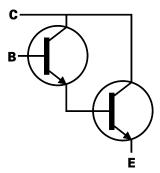
Mechanical Data

- Case: SOT223 (Type ZN)
- Case Material: Molded Plastic. "Green" Molding Compound;
 UL Flammability Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish—Matte Tin Plated Leads, Solderable per MIL-STD-202, Method 208
- Weight: 0.112 grams (Approximate)

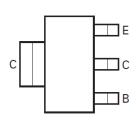




Top View



Device Symbol



Top View Pin-Out

Ordering Information (Notes 4 & 5)

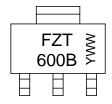
Product	Compliance	Marking	Reel Size (inches)	Tape Width (mm)	Quantity per reel
FZT600BQTA	Automotive	FZT600B	7	12	1000

Notes:

- 1. EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant. All applicable RoHS exemptions applied.
- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. Automotive products are AEC-Q101 qualified and are PPAP capable. Refer to https://www.diodes.com/quality/.
- 5. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

Marking Information

SOT223



FZT 600B = Product Type Marking Code (Group B) YWW = Date Code Marking Y or \overline{Y} = Last Digit of Year (ex: 8= 2018) WW or $\overline{W}W$ = Week Code (01~53)



Absolute Maximum Ratings ($@T_A = +25^{\circ}C$, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V _{CBO}	160	V
Collector-Emitter Voltage	V _{CEO}	140	V
Emitter-Base Voltage	V _{EBO}	10	V
Continuous Collector Current	Ic	2	Α
Peak Pulse Current	I _{CM}	4	Α

Thermal Characteristics ($@T_A = +25^{\circ}C$, unless otherwise specified.)

Characteristic	Symbol	Value	Unit		
	(Note 6)		3.0		
Power Dissipation	(Note 7)	Б	2.0	W	
Power Dissipation	(Note 8)	P_{D}	1.6		
	(Note 9)		1.2		
	(Note 6)		41.7		
Thermal Resistance, Junction to Ambient	(Note 7)	Б	62.5	°C/W	
Thermal Resistance, Junction to Ambient	(Note 8)	$R_{\Theta JA}$	78.1		
	(Note 9)		104		
Thermal Resistance Junction to Lead (Note 10)		R _{ÐJL}	12.9		
Operating and Storage Temperature Range	$T_{J,}T_{STG}$	-55 to +150	°C		

ESD Ratings (Note 11)

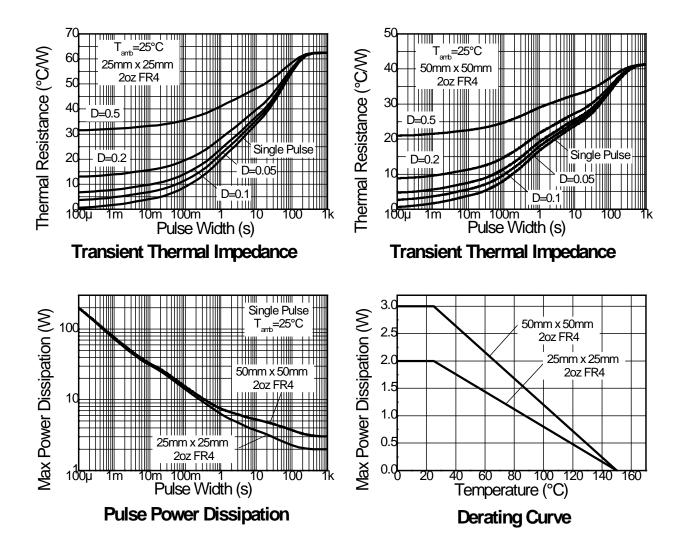
Characteristic	Symbol	Value	Unit	JEDEC Class
Electrostatic Discharge—Human Body Model	ESD HBM	2000	٧	2
Electrostatic Discharge—Machine Model	ESD MM	200	V	В

Notes:

- 6. For a device mounted with the collector lead on 50mm x 50mm 2oz copper that is on a single-sided 1.6mm FR4 PCB; device is measured under still air For a device mounted with the collector lead on 50mm x 50mm 2oz copper that is on a conditions whilst operating in a steady-state.
 Same as Note 6, except the device is mounted on 25mm x 25mm 2oz copper.
 Same as Note 6, except the device is mounted on 25mm x 25mm 1oz copper.
 Same as Note 6, except the device is mounted on minimum recommended pad layout.
 Thermal resistance from junction to solder-point (at the end of the collector lead).
 Refer to JEDEC specification JESD22-A114 and JESD22-A115.



Thermal Characteristics and Derating Information





Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

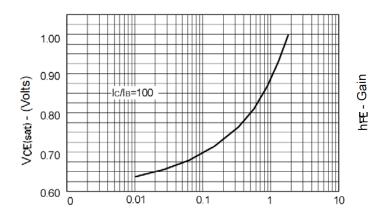
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
Collector-Base Breakdown Voltage	BV _{CBO}	160	_	_	V	$I_C = 100\mu A$
Collector-Emitter Breakdown Voltage (Note 12)	BV _{CEO}	140	_	_	V	I _C = 10mA
Emitter-Base Breakdown Voltage	BV _{EBO}	10	_	_	V	$I_E = 100\mu A$
Collector-Base Cut-Off Current	I _{CBO}	-	_	0.01 10	μΑ μΑ	V _{CB} = 140V V _{CB} = 140V, T _A = +100°C
Collector-Emitter Cut-Off Current	ICES	=	_	10	μΑ	V _{CES} = 140V
Emitter Cut-Off Current	I _{EBO}	ı	_	0.1	μΑ	V _{EB} = 8V
DC Current Gain (Note 12) (Group B)	h _{FE}	5000 10,000 5000	10,000 20,000 10,000	100,000 —		$I_C = 50$ mA, $V_{CE} = 10$ V $I_C = 500$ mA, $V_{CE} = 10$ V $I_C = 1$ A, $V_{CE} = 10$ V
Collector-Emitter Saturation Voltage (Note 12)	V _{CE(sat)}	-	0.75 0.85	1.1 1.2	V	$I_C = 500$ mA, $I_B = 5$ mA $I_C = 1$ A, $I_B = 10$ mA
Base-Emitter Saturation Voltage (Note 12)	V _{BE(sat)}	_	1.7	1.9	V	$I_C = 1A, I_B = 10mA$
Base-Emitter Turn-On Voltage (Note 12)	V _{BE(on)}	_	1.5	1.7	V	$I_{C} = 1A, V_{CE} = 5V$
Output Capacitance (Note 12)	C _{obo}	_	10	15	pF	V _{CB} = 10V, f = 1MHz
Current Gain-Bandwidth Product (Note 12)	f _T	150	250	_	MHz	V _{CE} = 10V, I _C = 100mA, f=20MHz
Turn-On Time	t _{on}	_	0.75	_	μs	V _{CC} = 10V, I _C = 500mA
Turn-Off Time	t _{off}		2.20		μs	$I_{B1} = -I_{B2} = 0.5 \text{mA}$

Note:

12. Measured under pulsed conditions. Pulse width \leq 300 μ s. Duty cycle \leq 2%.



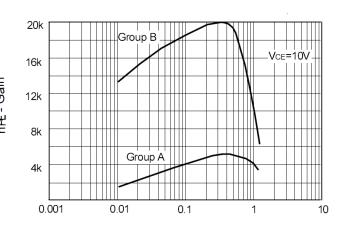
Typical Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)



Ic - Collector Current (Amps)

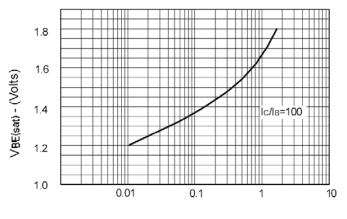
D.

VCE(sat) v IC



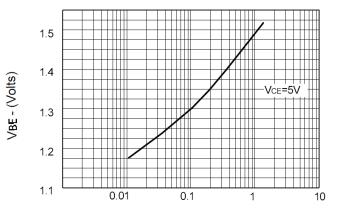
Ic - Collector Current (Amps)

hFE v IC



Ic - Collector Current (Amps)

VBE(sat) v IC



Ic - Collector Current (Amps)

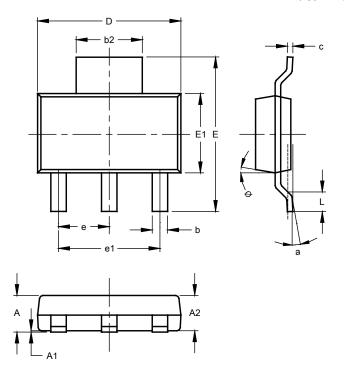
VBE(on) v IC



Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

SOT223 (Type ZN)

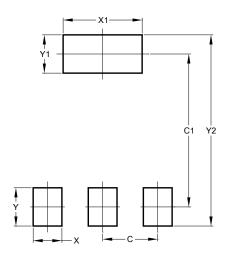


SOT223 (Type ZN)				
Dim	Min	Max	Тур	
Α		1.70		
A1	0.02	0.10		
A2	1.50	1.68	1.60	
b	0.60	0.80		
b2	2.90	3.10		
С	0.24	0.32		
D	6.30	6.70		
Е	6.70	7.30		
E1	3.30	3.70		
е	2.30 NOM			
e1	4.60 NOM			
L	0.90			
а			10°	
Φ		15°		
All Dimensions in mm				

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

SOT223 (Type ZN)



Dimensions	Value (in mm)
С	2.30
C1	6.40
Х	1.20
X1	3.30
Y	1.60
Y1	1.60
Y2	8.00

Note: For high voltage applications, the appropriate industry sector guidelines should be considered with regards to creepage and clearance distances between device terminals and PCB tracking.



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